

VIII. OPTIONAL LEAD FORM

Typically, SMD's are mounted .010" - .015" off the plane of the PCB. This clearance is specified to facilitate cleaning and visual inspection under the components. In some cases, the component is mounted flush to the PCB or on top of a heat sink for thermal dissipation.

There are basically three styles of SMD lead forms: *Gullwing*, "J Lead", and *Butt Mount*. The *Gullwing* shape has become the style of choice because of compliancy, inspection, and rework; although it takes up more real-estate than the "J" bend. There are some variations on the conventional *Gullwing*, such as the "*Camel-Hump*", which increases lead compliancy during thermal expansion or shock.

The foot angle may be in the same plane as the body, but depending upon the placement and soldering process, a toe-down or top-up configuration may be preferred. The heel of the foot must be coplanar within the JEDEC standard of +/- .002".

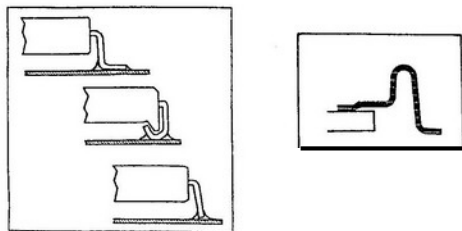


Figure 7: Camel Hump Form

Figure 6: Gullwing, "J" Lead, & Butt Mount Forms
(ICI Array Technology)